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- Members of the Texas Instruments
 Widebus™ Family
- State-of-the-Art Advanced BiCMOS Technology (ABT) Design for 3.3-V Operation and Low Static-Power Dissipation
- UBT™ (Universal Bus Transceiver)
 Combines D-Type Latches and D-Type
 Flip-Flops for Operation in Transparent, Latched, or Clocked Mode
- Support Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V V_{CC})
- Support Unregulated Battery Operation Down to 2.7 V
- Typical V_{OLP} (Output Ground Bounce)
 < 0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- I_{off} and Power-Up 3-State Support Hot Insertion
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Distributed V_{CC} and GND Pin Configuration
 Minimizes High-Speed Switching Noise
- Flow-Through Architecture Optimizes PCB Layout
- Latch-Up Performance Exceeds 500 mA Per JESD 17
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Package Options Include Plastic Shrink Small-Outline (DL) and Thin Shrink
 Small-Outline (DGG) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package
 Using 25-mil Center-to-Center Spacings

SN54LVTH16500 . . . WD PACKAGE SN74LVTH16500 . . . DGG OR DL PACKAGE (TOP VIEW)



description

The 'LVTH16500 devices are 18-bit universal bus transceivers designed for low-voltage (3.3-V) V_{CC} operation, but with the capability to provide a TTL interface to a 5-V system environment.

Data flow in each direction is controlled by output-enable (OEAB and OEBA), latch-enable (LEAB and LEBA), and clock (CLKAB and CLKBA) inputs. For A-to-B data flow, the device operates in the transparent mode when LEAB is high. When LEAB is low, the A data is latched if CLKAB is held at a high or low logic level. If LEAB is low, the A data is stored in the latch/flip-flop on the high-to-low transition of CLKAB. Output-enable OEAB is active high. When OEAB is high, the B-port outputs are active. When OEAB is low, the B-port outputs are in the high-impedance state.

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description (continued)

Data flow for B to A is similar to that of A to B but uses OEBA, LEBA, and CLKBA. The output enables are complementary (OEAB is active high and OEBA is active low).

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

When V_{CC} is between 0 and 1.5 V, the devices are in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 1.5 V, \overline{OE} should be tied to V_{CC} through a pullup resistor and OE should be tied to OE should be tied to OE through a pulldown resistor; the minimum value of the resistor is determined by the current-sinking/current-sourcing capability of the driver.

These devices are fully specified for hot-insertion applications using I_{off} and power-up 3-state. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down. The power-up 3-state circuitry places the outputs in the high-impedance state during power up and power down, which prevents driver conflict.

The SN54LVTH16500 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74LVTH16500 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE†

	OUTPUT			
OEAB	LEAB	CLKAB	В	
L	Х	Х	Χ	Z
Н	Н	Χ	L	L
Н	Н	Χ	Н	Н
Н	L	\downarrow	L	L
Н	L	\downarrow	Н	Н
Н	L	Н	Χ	в ₀ ‡
Н	L	L	Χ	в ₀ ‡ в ₀ §

[†] A-to-B data flow is shown: B-to-A flow is similar but uses OEBA, LEBA, and CLKBA.

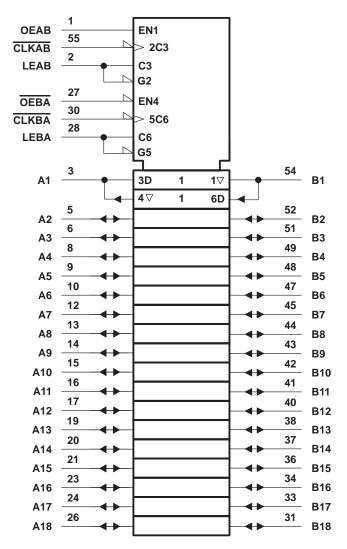


[‡] Output level before the indicated steady-state input conditions were established

[§] Output level before the indicated steady-state input conditions were established, provided that CLKAB was low before LEAB went low

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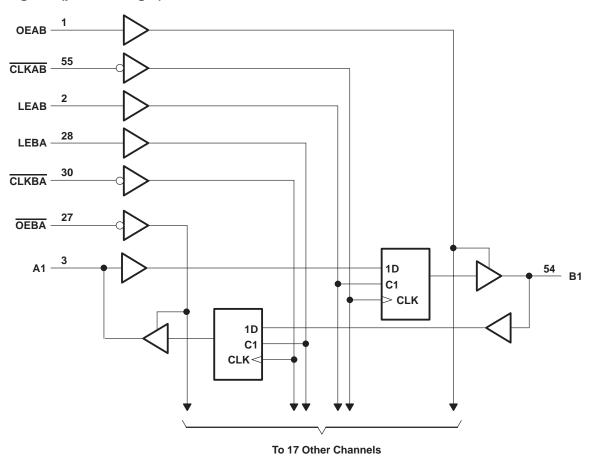
logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

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logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V _{CC}	
Input voltage range, V _I (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high-impedance	
or power-off state, V _O (see Note 1)	0.5 V to 7 V
Voltage range applied to any output in the high state, V _O (see Note 1)	$-0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Current into any output in the low state, IO: SN54LVTH16500	96 mA
SN74LVTH16500	
Current into any output in the high state, I _O (see Note 2): SN54LVTH16500	48 mA
SN74LVTH16500	64 mA
Input clamp current, I _{IK} (V _I < 0)	
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Package thermal impedance, θ _{JA} (see Note 3): DGG package	81°C/W
DL package	74°C/W
Storage temperature range, T _{stq}	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 - This current flows only when the output is in the high state and V_O > V_{CC}.
 The package thermal impedance is calculated in accordance with JESD 51.



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recommended operating conditions (see Note 4)

		SN54LVTI	H16500	SN74LVTI	UNIT		
			MIN	MAX	MIN	MAX	UNII
Vcc	Supply voltage		2.7	3.6	2.7	3.6	V
VIH	High-level input voltage		2	2	2		V
V _{IL}	Low-level input voltage		8.0		0.8	V	
VI	Input voltage		4	5.5		5.5	V
IOH	High-level output current		1	-24		-32	mA
loL	Low-level output current		22	48		64	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled	30/	10		10	ns/V
Δt/ΔV _{CC}	Power-up ramp rate		200		200		μs/V
TA	Operating free-air temperature		-55	125	-40	85	°C

NOTE 4: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS			4LVTH16	6500	SN7	UNIT					
PAR	KAWETER	1531 CC	SNOTTIONS	MIN	TYP†	MAX	MIN	TYP†	MAX	UNII			
VIK		$V_{CC} = 2.7 \text{ V},$	I _I = -18 mA			-1.2			-1.2	V			
VOH		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V},$	$I_{OH} = -100 \mu A$	V _{CC} -0	.2		V _{CC} -0	.2					
		$V_{CC} = 2.7 \text{ V},$	$I_{OH} = -8 \text{ mA}$	2.4			2.4						
		V _{CC} = 3 V	I _{OH} = -24 mA	2						'			
		VCC = 3 V	$I_{OH} = -32 \text{ mA}$				2						
		V _{CC} = 2.7 V	I _{OL} = 100 μA			0.2			0.2				
		vCC = 2.7 v	I _{OL} = 24 mA			0.5			0.5				
\ _{\/-} .			I _{OL} = 16 mA			0.4			0.4	V			
VOL		V2V	$I_{OL} = 32 \text{ mA}$			0.5	0.5			V			
		V _{CC} = 3 V	I _{OL} = 48 mA			0.55				1			
			I _{OL} = 64 mA						0.55	5			
	Control innuts	V _{CC} = 3.6 V,	$V_I = V_{CC}$ or GND			±1			±1				
	Control inputs	V _{CC} = 0 or 3.6 V,	V _I = 5.5 V	4 10			10						
Ц	A or B ports‡	V _{CC} = 3.6 V	V _I = 5.5 V		70	20	20			μΑ			
			$V_I = V_{CC}$	ر 1			1						
			V _I = 0		S	- 5			- 5				
l _{off}		$V_{CC} = 0$,	V_I or $V_O = 0$ to 4.5 V		9				±100	μΑ			
	A or B ports	V 2V	V _I = 0.8 V	75	7		75						
I _I (hold)		V _{CC} = 3 V	V _I = 2 V	– 75			- 75			μΑ			
		V _{CC} = 3.6 V§,	$V_{I} = 0 \text{ to } 3.6 \text{ V}$						±500				
lozpu		$\frac{\text{V}_{\text{CC}}}{\text{OE}/\text{OE}} = 0 \text{ to } 1.5 \text{ V}, \text{ V}_{\text{O}} = 0.5 \text{ V to } 3 \text{ V},$				±100*			±100	μА			
lozpd		$\frac{\text{V}_{\text{CC}}}{\text{OE}/\text{OE}} = 1.5 \text{ V to 0, V}_{\text{O}} = 0.5 \text{ V to 3 V,}$				±100*			±100	μА			
		V _{CC} = 3.6 V,	Outputs high			0.19			0.19				
Icc		$I_{O} = 0$,	Outputs low			5			5	mA			
		$V_I = V_{CC}$ or GND	Outputs disabled	0.19			0.19						
ΔICC¶		V _{CC} = 3 V to 3.6 V, One input at V _{CC} – 0.6 V, Other inputs at V _{CC} or GND				0.2			0.2	mA			
Ci		V _I = 3 V or 0			4			4		pF			
C _{io}		V _O = 3 V or 0			10			10		pF			

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.



[†] All typical values are at V_{CC} = 3.3 V, T_{A} = 25°C. ‡ Unused pins at V_{CC} or GND

[§] This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

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timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

					SN54LVTH16500			5						
				$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V} $ $V_{CC} = 2.7 \text{ V}$		V _{CC} = 3.3 V ± 0.3 V		V _{CC} = 2.7 V		UNIT				
				MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX			
fclock	f _{clock} Clock frequency				150		150		150		150	MHz		
	Pulse duration	LE high		3.3		3.3		3.3		3.3		ns		
t _W		CLK high or low		3.3		3.3		3.3		3.3		115		
	Setup time	A before CLKAB↓		3.1		3.1		2.9		2.9				
_		B before CLKBA↓		3.1		3.1		2.9		2.9				
t _{su}		Setup time	·	A D b - (1 5 1	CLK high	1.5	2	0.6		1.4		0.5		ns
		A or B before LE↓	CLK low	3.1	000	2.5		2.9		2.3				
t.	Hold time	A or B after CLK↓	-	0.4	Q"	0.4		0.4		0.4		ns		
th		A or B after LE↓		1.7		1.7		1.6		1.6		115		

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

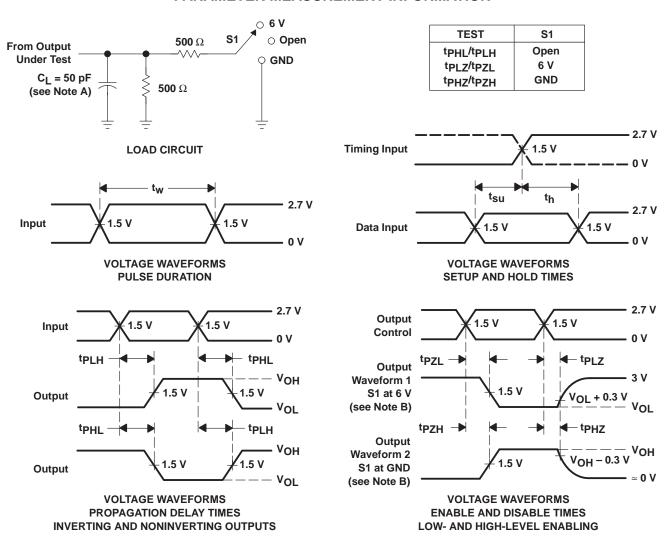
				SN54LVTH16500								
PARAMETER	FROM (INPUT)	TO (OUTPUT)	1 00		V _{CC} = 2.7 V		V _{CC} = 3.3 V ± 0.3 V			V _{CC} = 2.7 V		UNIT
			MIN	MAX	MIN	MAX	MIN	TYP [†]	MAX	MIN	MAX	
f _{max}			150		150		150			150		MHz
t _{PLH}	D or A	A or B	1.2	3.9		4.1	1.3	2.8	3.7		4	ns
t _{PHL}	B or A	AUIB	1.2	3.9	2	4.1	1.3	2.6	3.7		4	115
t _{PLH}	LEDALEAD	A or B	1.4	5.5	, Z	5.9	1.5	3.8	5.1		5.7	ns
t _{PHL}	LEBA or LEAB	AOIB	1.4	5.5	17/4	5.9	1.5	3.8	5.1		5.7	115
t _{PLH}	CLKBA or	A or B	1.2	5.3		6.1	1.3	3.6	5		5.9	ns
^t PHL	CLKAB	AOIB	1.2	5.3		6.1	1.3	3.5	5		5.9	115
^t PZH	OFDA -	A or B	1.2	5.1		5.8	1.3	3.6	4.8		5.5	ns
t _{PZL}	OEBA or OEAB	AUIB	1.2	5.1		5.8	1.3	3.6	4.8		5.5	115
^t PHZ	OEBA or OEAB	A or B	1.6	6.1		6.6	1.7	4.5	5.8		6.3	ns
t _{PLZ}	OLDA UI OEAD	AUD	1.6	6.1		6.6	1.7	4.1	5.8		6.3	113

 $[\]dagger$ All typical values are at V_{CC} = 3.3 V, T_A = 25°C.



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PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_I includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_{O} = 50 \Omega$, $t_{r} \leq 2.5$ ns. $t_{f} \leq 2.5$ ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

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